

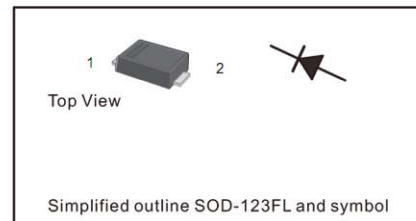
● Surface Mount Superfast Recovery Rectifier

Reverse Voltage – 50 to 600 V

Forward Current – 1 A

● Features

- Easy pick and place
- For surface mounted applications
- Low profile package
- Built-in strain relief
- Superfast recovery times for high efficiency



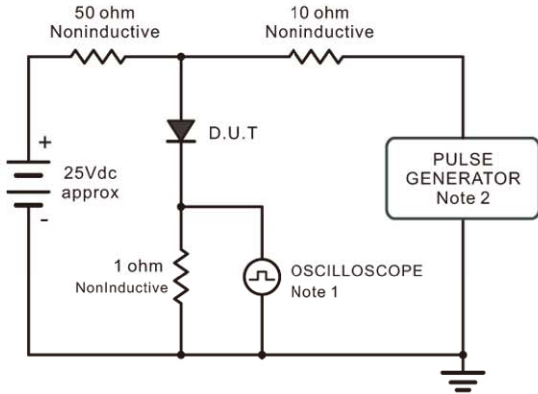
● Absolute Maximum Ratings and Characteristics

Ratings at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Parameter	Symbols	ES1AW	ES1BW	ES1CW	ES1DW	ES1EW	ES1GW	ES1JW	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	150	200	300	400	600	V
Maximum RMS voltage	V_{RMS}	35	70	105	140	210	280	420	V
Maximum DC Blocking Voltage	V_{DC}	50	100	150	200	300	400	600	V
Maximum Average Forward Rectified Current at $T_L = 100\text{ °C}$	$I_{F(AV)}$	1							A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	25							A
Maximum Forward Voltage at 1 A	V_F	1				1.25		1.7	V
Maximum DC Reverse Current at Rated DC Blocking Voltage $T_a = 25\text{ °C}$ $T_a = 125\text{ °C}$	I_R	5 100							μA
Typical Junction Capacitance at $V_R=4\text{V}$, $f=1\text{MHz}$	C_j	10							pF
Maximum Reverse Recovery Time at $I_F=0.5\text{A}$, $I_R=1\text{A}$, $I_{rr}=0.25\text{A}$	t_{rr}	35							ns
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150							$^{\circ}\text{C}$



Fig.1 Reverse Recovery Time Characteristic And Test Circuit Diagram



Note: 1. Rise Time = 7ns, max.
Input Impedance = 1megohm, 22pF.
2. Rise Time = 10ns, max.
Source Impedance = 50 ohms.

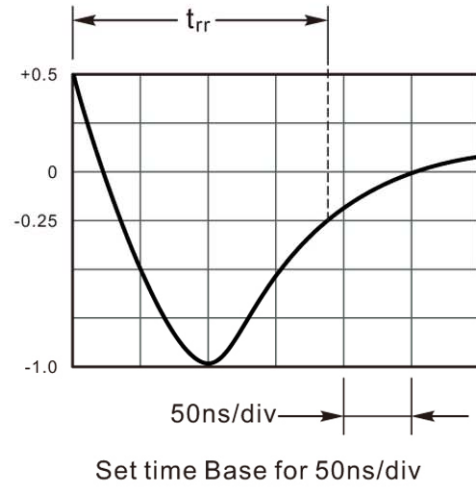


Fig.2 Maximum Average Forward Current Rating

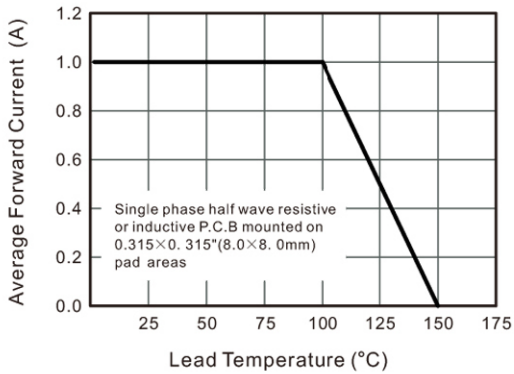


Fig.3 Typical Reverse Characteristics

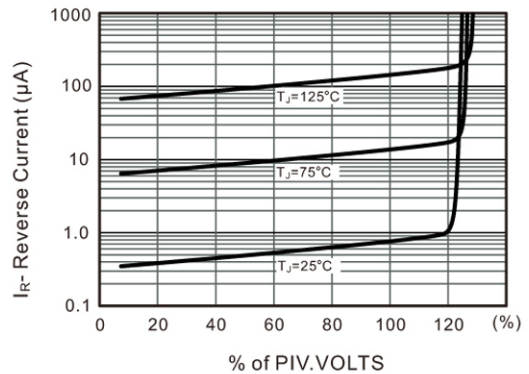


Fig.4 Typical Forward Characteristics

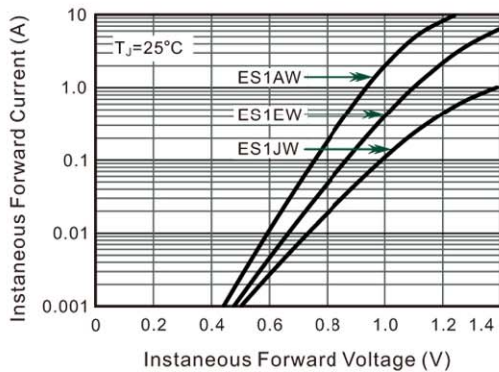
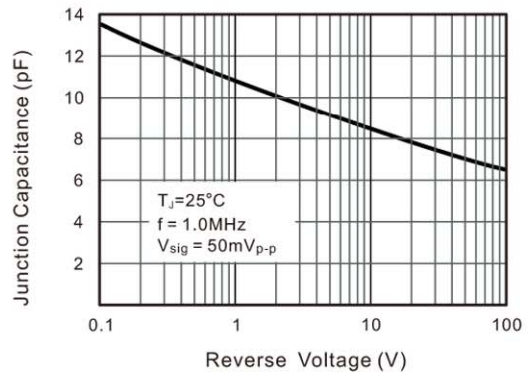
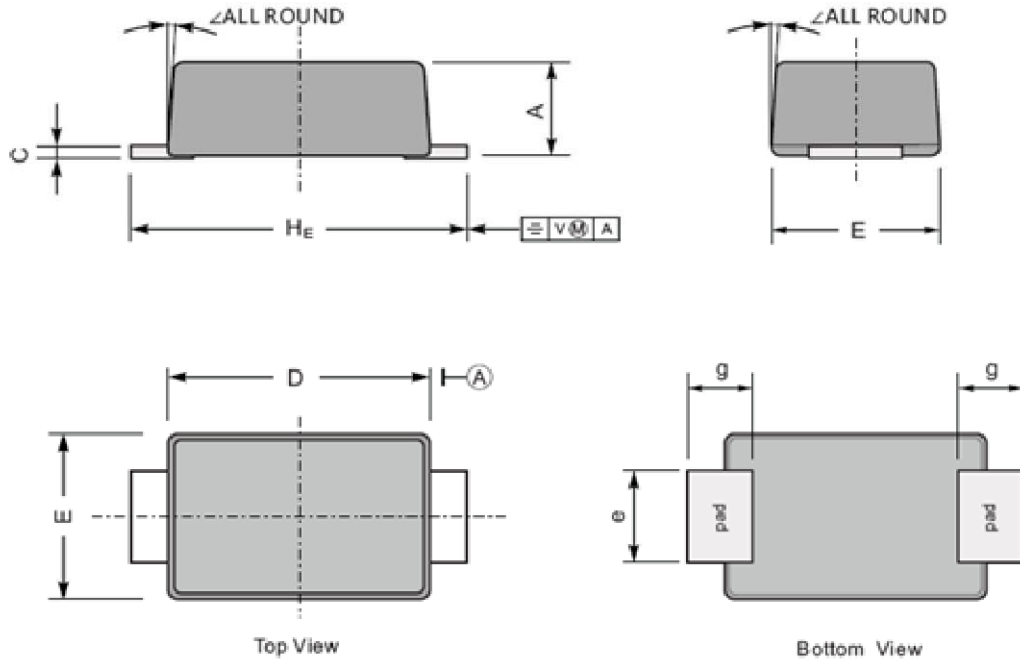


Fig.5 Typical Junction Capacitance



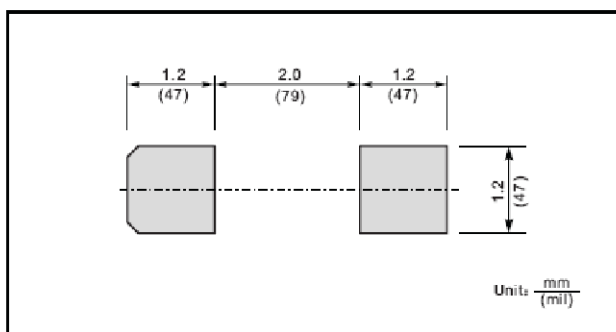
PACKAGE OUTLINE

Plastic surface mounted package; 2 leads



UNIT		A	C	D	E	e	g	H_E	\angle
mm	max	1.1	0.20	2.9	1.9	1.1	0.9	3.8	7°
	min	0.9	0.12	2.6	1.7	0.8	0.7	3.5	
mil	max	43	7.9	114	75	43	35	150	
	min	35	4.7	102	67	31	28	138	

The recommended mounting pad size

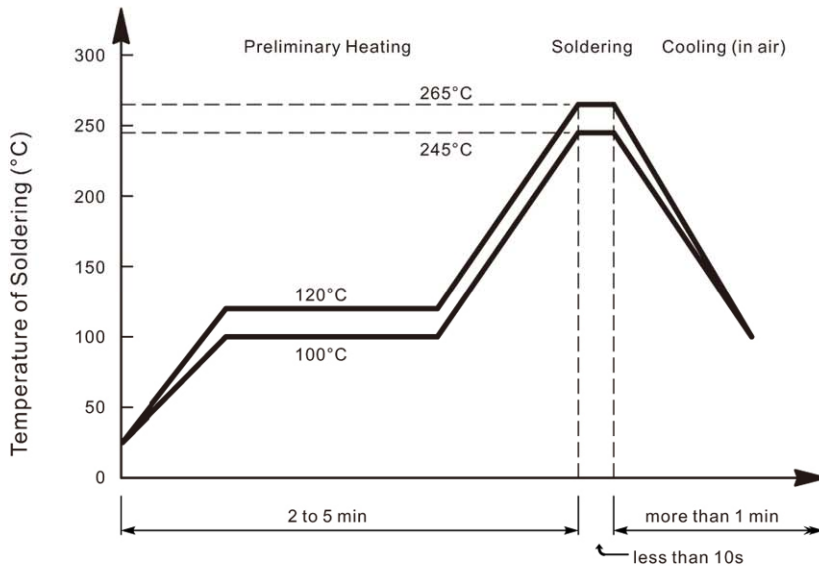


Marking

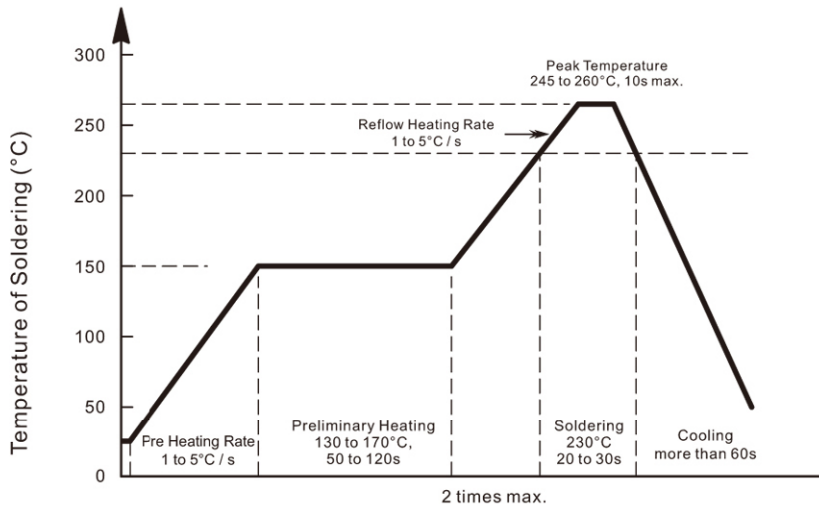
Type number	Marking code
ES1AW	E1A
ES1BW	E1B
ES1CW	E1C
ES1DW	E1D
ES1EW	E1E
ES1GW	E1G
ES1JW	E1J



• Recommended condition of flow soldering



• Recommended condition of reflow soldering



Recommended peak temperature is over 245 °C. If peak temperature is below 245 °C, you may adjust the following parameters; time length of peak temperature (longer), time length of soldering (longer), thickness of solder paste (thicker)

• Condition of hand soldering

Temperature: 370°C
 Time: 3s max.
 Times: one time

• Remark:

Lead free solder paste (96.5Sn/3.0Ag/0.5Cu)

